

ABSTRACT

The invention proposes a power semiconductor module with a housing (1) that consists of a hardenable plastic casting compound and a base plate (2), wherein electric power semiconductor components (4) are arranged on a section of the surface of the base plate (2) that faces the housing (1) by means of an insulating layer (5). At least the section of the surface of the base plate (2) that faces of the housing (1) and contains the electric power semiconductor components (4) is encapsulated in the housing(), wherein the hardenable plastic casting compound has a hardness between 30 and 95 ShoreA.

Figure 1